

• General Description

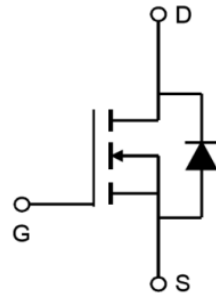
AP3406A combines advanced MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is most suitable to load-switch or PWM applications.

• Applications

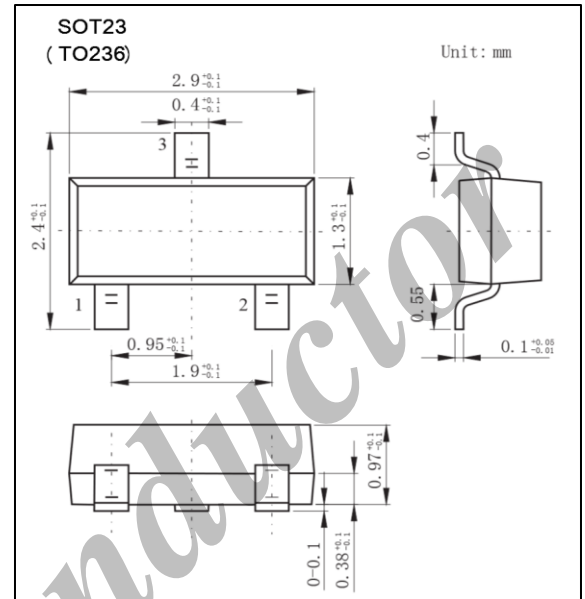
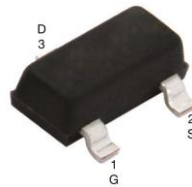
- DC/DC converter for portable devices
- Load switch

• Product Summary

| | |
|------------------------------------|----------------|
| V_{DS} | 30V |
| I_D (at $V_{GS} = 10V$) | 3.6A |
| $R_{DS(ON)}$ (at $V_{GS} = 10V$) | < 50m Ω |
| $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) | < 70m Ω |



Top View



• Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit | |
|---|-----------------|------------------------|------------------|--------------------|
| Drain-Source Voltage | V_{DS} | 30 | V | |
| Gate-Source Voltage | V_{GS} | ± 20 | | |
| Continuous Drain Current | I_D | $T_A=25^\circ\text{C}$ | 3.6 | A |
| | | $T_A=70^\circ\text{C}$ | 2.9 | |
| Pulsed Drain Current * C | I_{DM} | 15 | | |
| Power Dissipation ^B | P_D | $T_A=25^\circ\text{C}$ | 1.4 | W |
| | | $T_A=70^\circ\text{C}$ | 0.9 | |
| Thermal Resistance. Junction- to-Ambient ^{A D} | $R_{\theta JA}$ | $t \leq 10s$ | 90 | $^\circ\text{C/W}$ |
| | | Steady State | 125 | |
| Thermal Resistance. Junction- to-Lead (Steady State) | $R_{\theta JL}$ | 80 | | |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ | |
| Storage Temperature Range | T_{STG} | -55 to 150 | | |

* Repetitive rating, pulse width limited by junction temperature.

• **Electrical Characteristics Ta = 25°C**

| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|---------------------------------------|--------------|--|-----|------|-----------|------------|
| Drain-Source Breakdown Voltage | V_{DSS} | $I_D=250\mu A, V_{GS}=0V$ | 30 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=30V, V_{GS}=0V$ | | | 1 | μA |
| | | $V_{DS}=30V, V_{GS}=0V, T_J=55^\circ C$ | | | 5 | |
| Gate-Body leakage current | I_{GSS} | $V_{DS}=0V, V_{GS}=\pm 20V$ | | | ± 100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.5 | 2 | 2.5 | V |
| Static Drain-Source On-Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=3.6A$ | | 36 | 50 | m Ω |
| | | $V_{GS}=10V, I_D=3.6A, T_J=125^\circ C$ | | 57 | 80 | |
| | | $V_{GS}=4.5V, I_D=2.8A$ | | 48 | 70 | |
| On State Drain Current | $I_{D(on)}$ | $V_{GS}=10V, V_{DS}=5V$ | 15 | | | A |
| Forward Transconductance | g_{FS} | $V_{DS}=5V, I_D=3.6A$ | | 11 | | S |
| Input Capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=15V, f=1MHz$ | | 170 | 210 | pF |
| Output Capacitance | C_{oss} | | | 35 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 23 | | |
| Gate Resistance | R_g | $V_{GS}=0V, V_{DS}=0V, f=1MHz$ | 1.7 | 3.5 | 5.3 | Ω |
| Total Gate Charge | Q_g | $V_{GS}=4.5V, V_{DS}=15V, I_D=3.6A$ | | 2 | 3 | nC |
| | | | | 4.05 | 5 | |
| Gate Source Charge | Q_{gs} | $V_{GS}=10V, V_{DS}=15V, I_D=3.6A$ | | 0.55 | | |
| Gate Drain Charge | Q_{gd} | | | 1 | | |
| Turn-On Delay Time | $t_{D(on)}$ | $V_{GS}=10V, V_{DS}=15V, R_L=2.2\Omega, R_{GEN}=3\Omega$ | | 4.5 | | ns |
| Turn-On Rise Time | t_r | | | 1.5 | | |
| Turn-Off Delay Time | $t_{D(off)}$ | | | 18.5 | | |
| Turn-Off Fall Time | t_f | | | 15.5 | | |
| Body Diode Reverse Recovery Time | t_{rr} | | | 7.5 | 10 | |
| Body Diode Reverse Recovery Charge | Q_{rr} | $I_F=3.6A, dI/dt=100A/\mu s$ | | 2.5 | | nC |
| Maximum Body-Diode Continuous Current | I_S | | | | 1.5 | A |
| Diode Forward Voltage | V_{SD} | $I_S=1A, V_{GS}=0V$ | | 0.79 | 1 | V |

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ C$, using $\leq 10s$ junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ C$.

D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu s$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}=150^\circ C$. The SOA curve provides a single pulse rating.

• **Ordering Information**

| Ordering Part Number | Package | MOQ |
|----------------------|---------------|------------------|
| AP3406A | SOT23 (T0236) | 3,000 pcs / reel |

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• Typical Characteristics

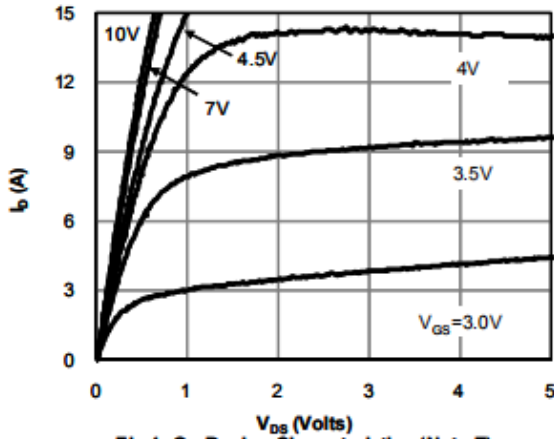


Fig 1: On-Region Characteristics (Note E)

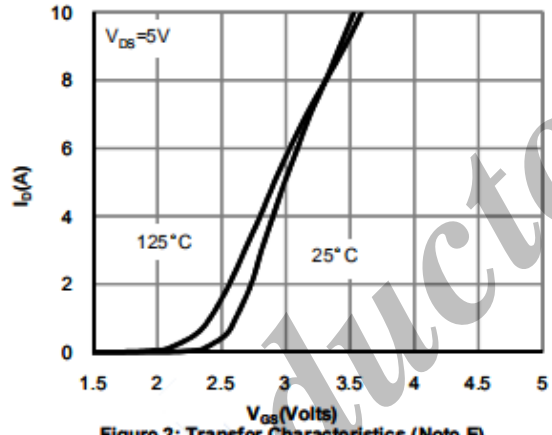


Figure 2: Transfer Characteristics (Note E)

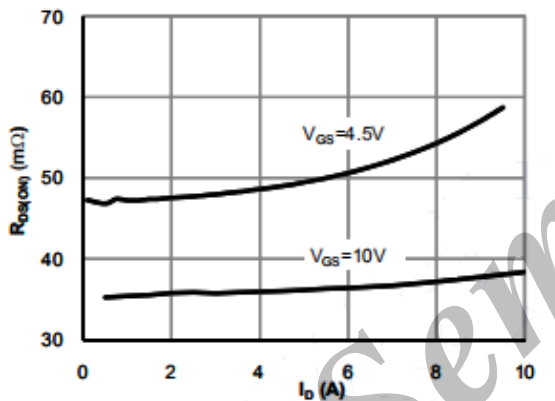


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

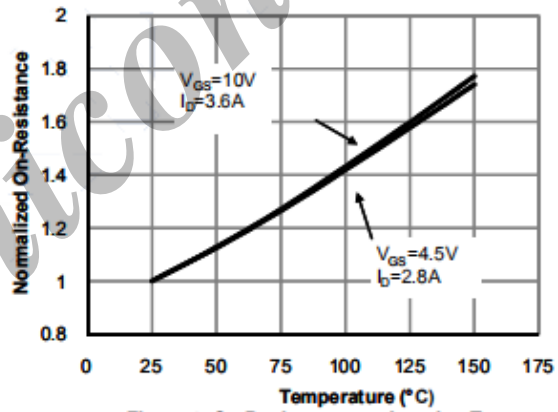


Figure 4: On-Resistance vs. Junction Temperature (Note E)

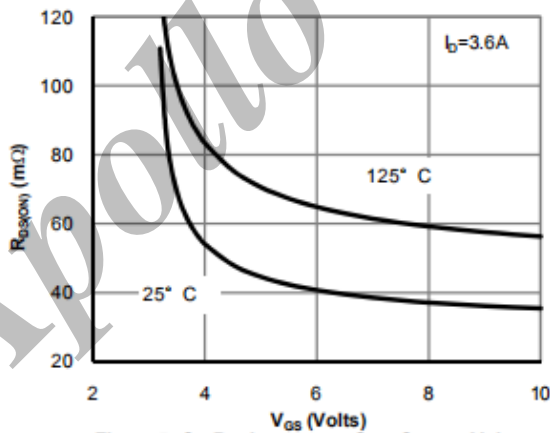


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

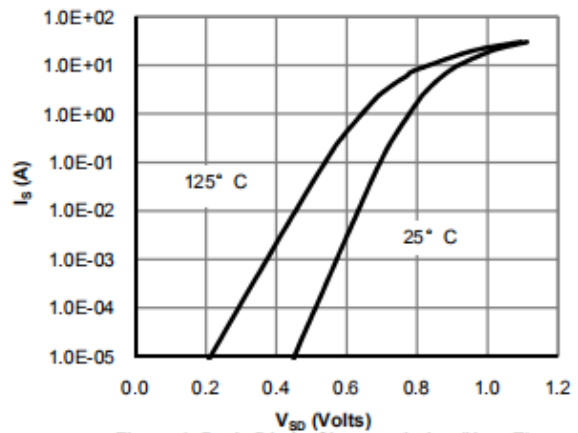


Figure 6: Body-Diode Characteristics (Note E)

• Typical Characteristics

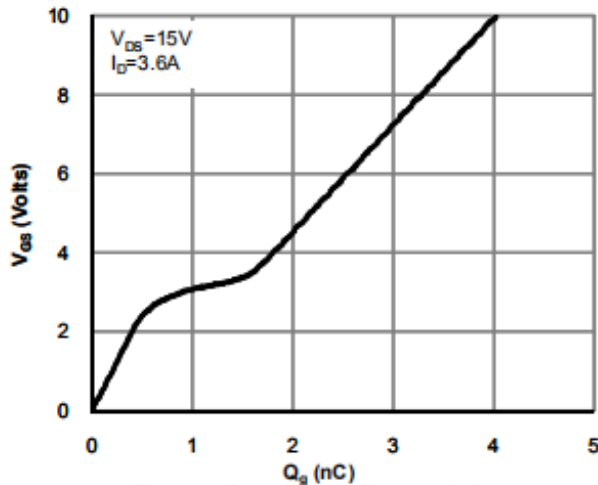


Figure 7: Gate-Charge Characteristics

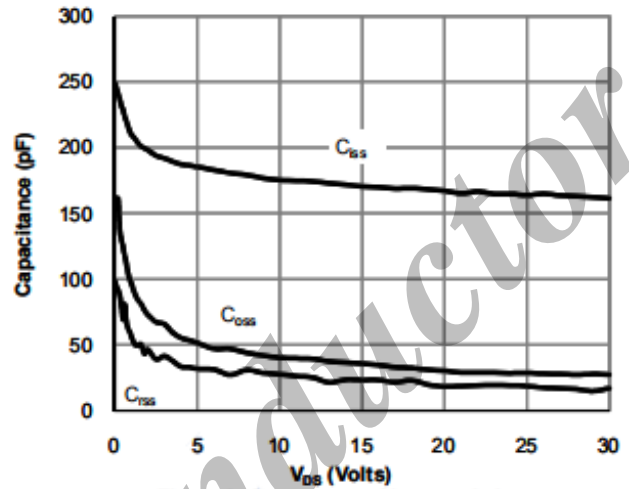


Figure 8: Capacitance Characteristics

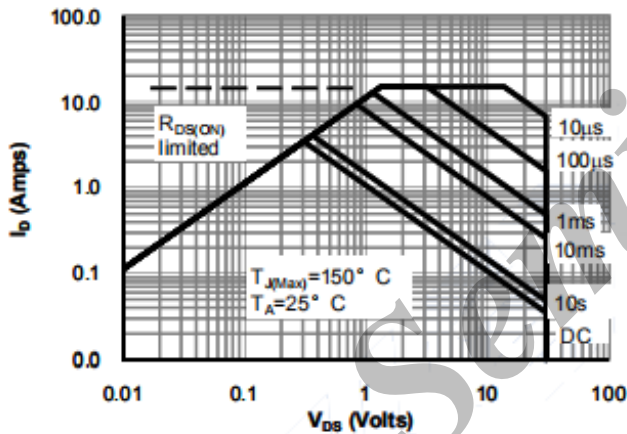


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

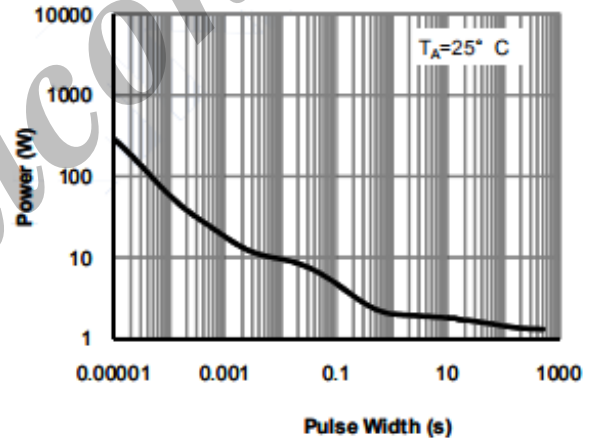


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

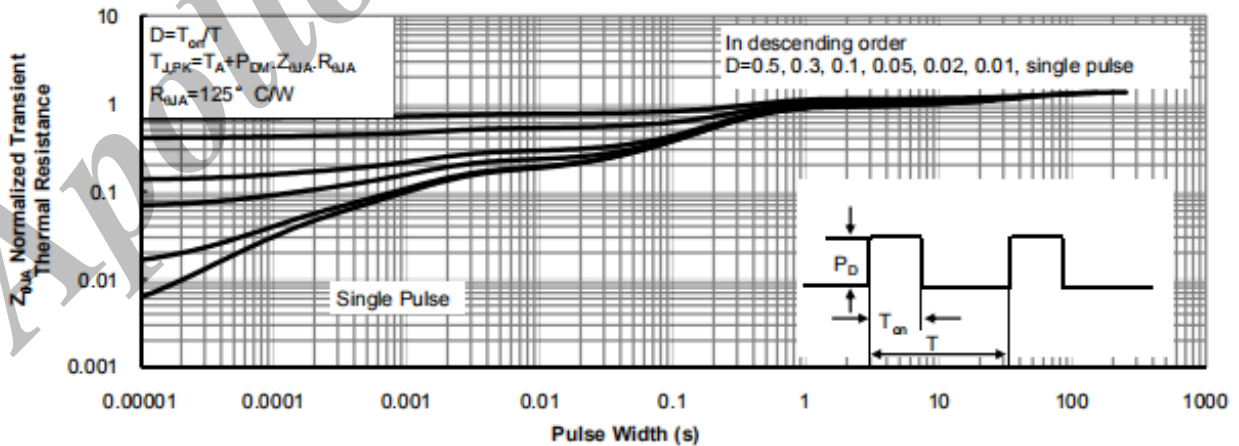


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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